

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7473569

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ZVI OR-BACH	08/06/2022
BRIAN CRONQUIST	08/06/2022
RECEIVING PARTY DATA	
Name:	MONOLITHIC 3D INC.
Street Address:	1662 COVE POINT RD
City:	KLAMATH FALLS
State/Country:	OREGON
Postal Code:	97601
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17882607
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	4088399533
Email:	Brian@Monolithic3D.com
Correspondent Name:	BRIAN CRONQUIST
Address Line 1:	1662 COVE POINT RD
Address Line 4:	KLAMATH FALLS, OREGON 97601
ATTORNEY DOCKET NUMBER:	M3D-HR7CON14-CDP
NAME OF SUBMITTER:	BRIAN CRONQUIST
SIGNATURE:	/Brian Cronquist/
DATE SIGNED:	08/08/2022
Total Attachments: 2	
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source=M3D-HR7con14-cdp_Assignment_Brian---signed#page1.tif	

ASSIGNMENT

Whereas, I, **Zvi Or-Bach** (hereinafter referred to as **Assignor(s)**), residing in **Haifa, Israel**; have made a certain invention, and executed United States Patent Application entitled:

**3D SEMICONDUCTOR DEVICE AND STRUCTURE
WITH METAL LAYERS**

as described in U.S. Patent Application Serial No. 17/tbd and filed on or about August 06, 2022; and

Whereas, Monolithic 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 976091 US (hereinafter called “Assignee”), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the “Designated Countries”).

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

DATE on 08 / 06 / 2022

(**Zvi**

First Name

20-1/10 '23

Or-Bach)

Last Name

PATENT

REEL: 060743 FRAME: 0070 f3821e9

ASSIGNMENT

Whereas, I, **Brian Cronquist (hereinafter referred to as Assignor(s)), residing in Klamath Falls, Oregon;** have made a certain invention, and executed United States Patent Application entitled:

**3D SEMICONDUCTOR DEVICE AND STRUCTURE
WITH METAL LAYERS**

as described in U.S. Patent Application Serial No. 17/tbd and filed on or about August 06, 2022; and

Whereas, Monolithic 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 976091 US (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

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I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

Brian Cronquist

DATE on 08 / 06 / 2022

(Brian

Cronquist)

First Name

Middle Initial

Last Name